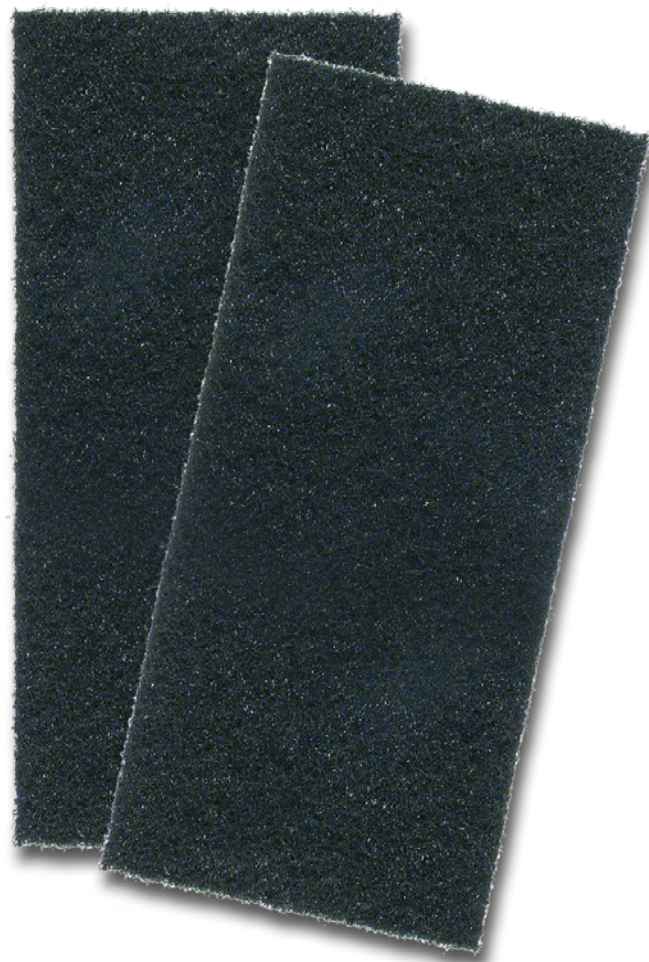# Univlies® Cleaning Pads
- by Unipak

Univlies® Cleaning pads for cleaning solder areas.

Univlies are metal-free sanding sponges for preparation and cleaning of areas to be soldered.

Soldering is a method of joining metal parts, where two or more items are joined with a melted material - Unitin or Unisilver. The soldering process takes places by heating the parts to be joined to a temperature lower than their melting temperature. Thereby, the solder metal melts and flows onto the solder pieces. During solidification, a metallic bond appears between the solder items, which creates the solder joint itself.

Soldering is divided into soft or hard soldering. Soft soldering with Unitin is carried out at temperatures below 450 °C, hard soldering with Unisilver at 450 °C - 480 °C.

A precondition for a correct solder joint to be created is that the melted material is able to flow onto the solder items to be joined. If the surface is contaminated with grease, dirt or oxides, direct contact between the solders and solder is prevented.

Univlies is used precisely for removing dirt and oxidation layers, so that a precondition is created for a correct solder joint. The solder items are cleaned with Univllies as the cleaning pads are rubbed / scrubbed hard against the area that will later be applied with solder. Univlies are used both for preparing the soldering area for both hard and soft soldering.

Packaging		Vare-nr.	EAN no.	VVS no.	RSK no.	NRF no.	LVI no.
Univlies 130 x 60 mm	10 pcs.	4580311	5708923458315	043078006	9507933	9507933	7075352
Univlies 230 x 150 mm	10 pcs.	4580813	5708923905734	043078115	1885836	9518009	7076865

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Additional product information, safety data sheets, demo videos, instructions for use, etc. can be found at: www.unipak.dk
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We cannot assume responsibility for the results obtained by others over whose methods we have no control.
It is the user's responsibility to determine suitability for the user's purpose of any application methods mentioned herein.